

In the Claims

CONFIRMATION OF CLAIMS 6 AND 8 RENDERED UNREADABLE BY PUNCH HOLES MADE BY USPTO HOLE PUNCHING.

6. The apparatus of claim 4 wherein the first wavelength is less than the second wavelength.
8. An apparatus for processing a diamond film substrate, said apparatus comprising:
- (a) a holder for receiving the diamond film substrate; and
 - (b) a first laser system configured to first direct a first wavelength of laser light toward the holder at a diamond film substrate having a surface, said surface having an initial surface roughness, R_0 , to both evaporate a portion of the substrate surface and create a structurally weakened surface having an intermediate surface roughness, R_i ; and
 - (c) a second laser system configured to subsequently direct a second wavelength of laser light to at least a portion of the structurally weakened substrate surface having an intermediate surface roughness, R_i , to remove the structurally weakened surface to modify the surface of at least a part of said portion to a final surface roughness, R_f ;
- whercin said first and second wavelengths of laser light are different wavelengths of laser light.